## nexperia

## **Quarterly Reliability Monitoring Results**

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

Supplier		User Part Number						
Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		PTVS16VS1UTR-Q						
		Part Description						
		Nexperia DHAM	Protection					
		SMD package						
		Test Conditions	Duration	# Lots	# Quantity	# Rejects		
	TEST							
	Pre- and Post-Stress							
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below		
		JESD22-A113						
		Bake Tamb = 125 °C	24 hours					
	PC	Soak Tamb = 85 °C, RH = 85%	168 hours					
# A1	Preconditioning	Reflow soldering	3 cycles	524	22940	0		
		MIL-STD-750-1						
	HTRB	M1038 Method A						
# D1	Bias	Tj = Tjmax, Vr = 100% of max. datasheet reverse voltage	1000 hours	205	0400	0		
# B1	Dias	Teverse voltage	1000 hours	205	9400	0		
	тс	JESD22-A104						
# A4	Temperature Cycling	-65 °C to Tjmax, not to exceed 150°C	1000 cycles	156	7080	0		
# A4	remperature cycing		1000 Cycles	150	7000	0		
	UHAST	JESD22-A118						
# A3 <b>or</b> # A3 alt	Unbiased HAST	Tamb = 130 °C, RH = 85 %		156	7080	0		
		JESD22-A102	— 96 hours					
	AC	Tamb = $121 ^{\circ}C$ , RH = $100 ^{\circ}M$						
	Autoclave	Pressure = 205 kPa (29.7 psia)						
	H3TRB	JESD22-A101						
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of						
# A2 alt	Temperature Reverse Bias	rated reverse voltage <sup>[1]</sup>	1000 hours	156	7080	0		
		MIL-STD-750 Method 1037						
	IOL	ton = toff, devices powered to insure $\Delta Tj$ =						
# A5	Intermittent Operating Life	100 °C for 15000 cycles	1000 hours	n.a.	n.a.	n.a.		
	RSH	JESD22-A111						
# C8	Resistance to Solder Heat	260 °C ± 5 °C	10 s	56	1700	0		
	SD Caldershility	1 CTD 002						
# C10	Solderability	J-STD-002		56	1700	0		

[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia DHAM	Protection	9400	0	0,45	2,21E+09

© 2024 Nexperia B.V.

All information hereunder is per Nexperia's best knowledge. This document does not provide for any representation or warranty express or implied by Nexperia. In case Nexperia has tested the product, this documentation reflects the outcome of the analysis of the actually tested parts only.

nexperia.com